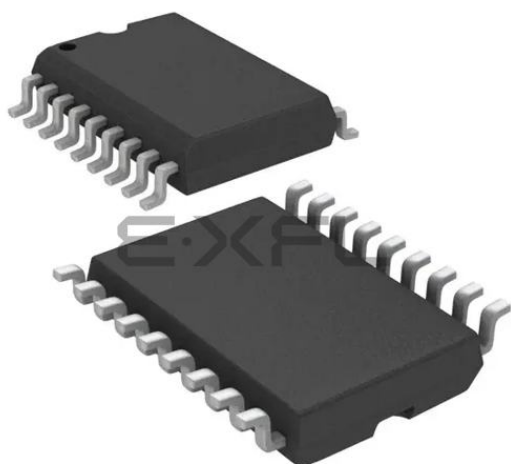




Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c56-10i-so

6.0 MEMORY ORGANIZATION

PIC16C5X memory is organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one or two STATUS Register bits. For devices with a data memory register file of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Selection Register (FSR).

6.1 Program Memory Organization

The PIC16C54, PIC16CR54 and PIC16C55 have a 9-bit Program Counter (PC) capable of addressing a 512 x 12 program memory space (Figure 6-1). The PIC16C56 and PIC16CR56 have a 10-bit Program Counter (PC) capable of addressing a 1K x 12 program memory space (Figure 6-2). The PIC16C57, PIC16C58 and PIC16CR58 have an 11-bit Program Counter (PC) capable of addressing a 2K x 12 program memory space (Figure 6-3). Accessing a location above the physically implemented address will cause a wraparound.

A NOP at the RESET vector location will cause a restart at location 000h. The RESET vector for the PIC16C54, PIC16CR54 and PIC16C55 is at 1FFh. The RESET vector for the PIC16C56 and PIC16CR56 is at 3FFh. The RESET vector for the PIC16C57, PIC16CR57, PIC16C58, and PIC16CR58 is at 7FFh. See Section 6.5 for additional information using CALL and GOTO instructions.

FIGURE 6-1: PIC16C54/CR54/C55 PROGRAM MEMORY MAP AND STACK

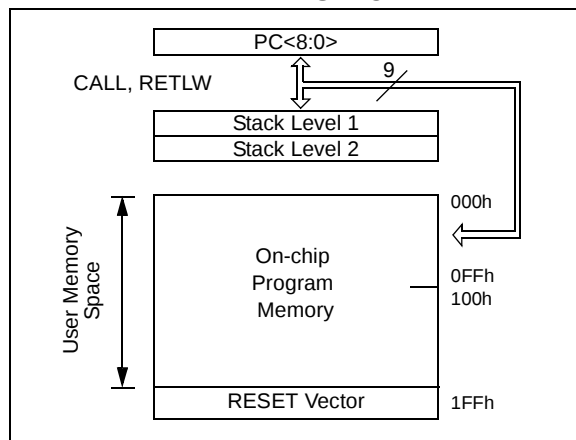


FIGURE 6-2: PIC16C56/CR56 PROGRAM MEMORY MAP AND STACK

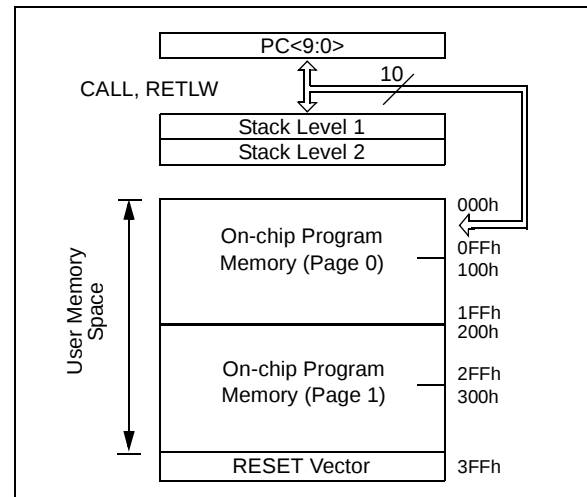
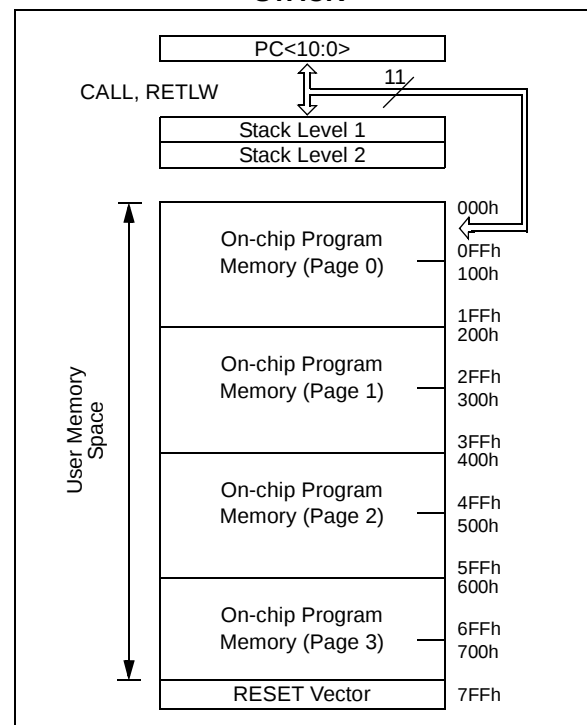


FIGURE 6-3: PIC16C57/CR57/C58/CR58 PROGRAM MEMORY MAP AND STACK



PIC16C5X

NOTES:

13.0 ELECTRICAL CHARACTERISTICS - PIC16CR54A

Absolute Maximum Ratings^(†)

Ambient Temperature under bias	–55°C to +125°C
Storage Temperature	–65°C to +150°C
Voltage on V _{DD} with respect to V _{SS}	0 to +7.5V
Voltage on MCLR with respect to V _{SS} ⁽¹⁾	0 to +14V
Voltage on all other pins with respect to V _{SS}	–0.6V to (V _{DD} + 0.6V)
Total power dissipation ⁽²⁾	800 mW
Max. current out of V _{SS} pin	150 mA
Max. current into V _{DD} pin	50 mA
Max. current into an input pin (TOCKI only)	±500 µA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O port (PORTA or B)	40 mA
Max. output current sunk by a single I/O port (PORTA or B)	50 mA

Note 1: Voltage spikes below V_{SS} at the MCLR pin, inducing currents greater than 80 mA may cause latch-up. Thus, a series resistor of 50 to 100 Ω should be used when applying a low level to the MCLR pin rather than pulling this pin directly to V_{SS}.

2: Power Dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 13-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16CR54A

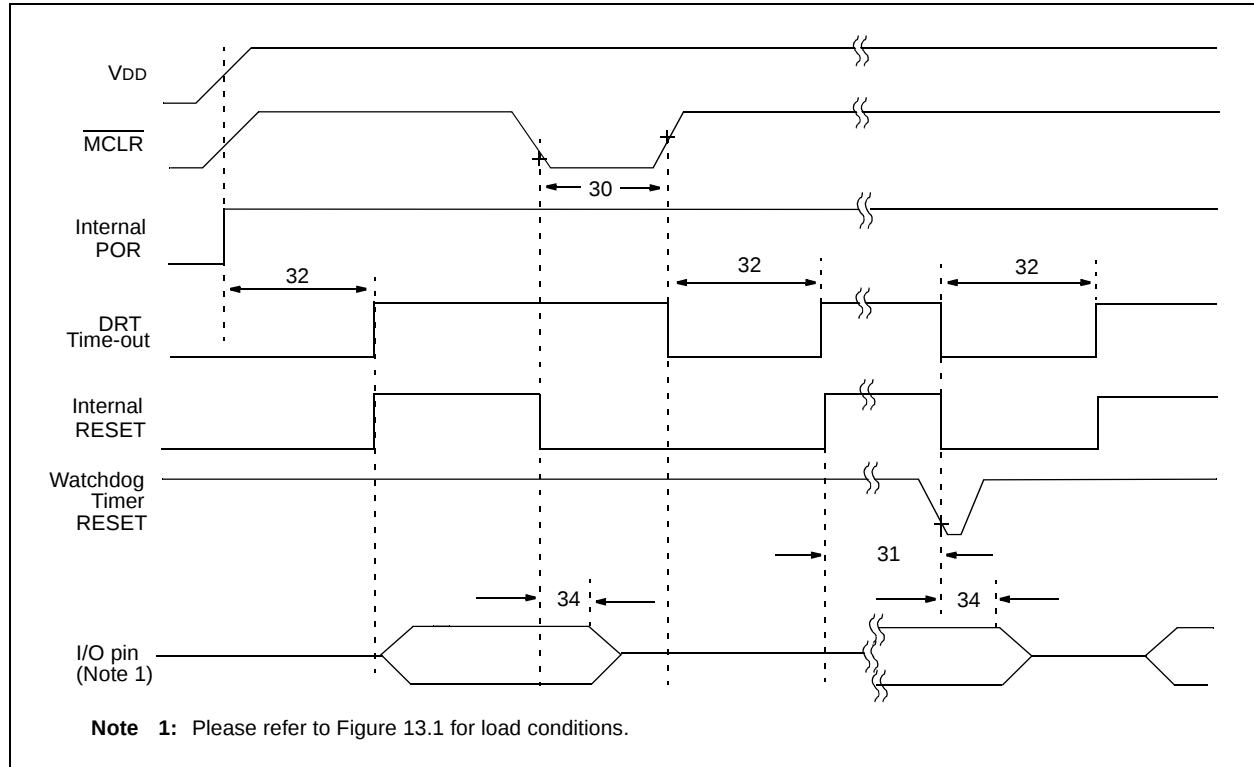


TABLE 13-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16CR54A

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics		Operating Temperature					
		0°C ≤ TA ≤ +70°C for commercial					
		–40°C ≤ TA ≤ +85°C for industrial					
		–40°C ≤ TA ≤ +125°C for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmCL	MCLR Pulse Width (low)	1.0*	—	—	μs	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7.0*	18*	40*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	7.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	—	—	1.0*	μs	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C5X

FIGURE 13-5: TIMER0 CLOCK TIMINGS - PIC16CR54A

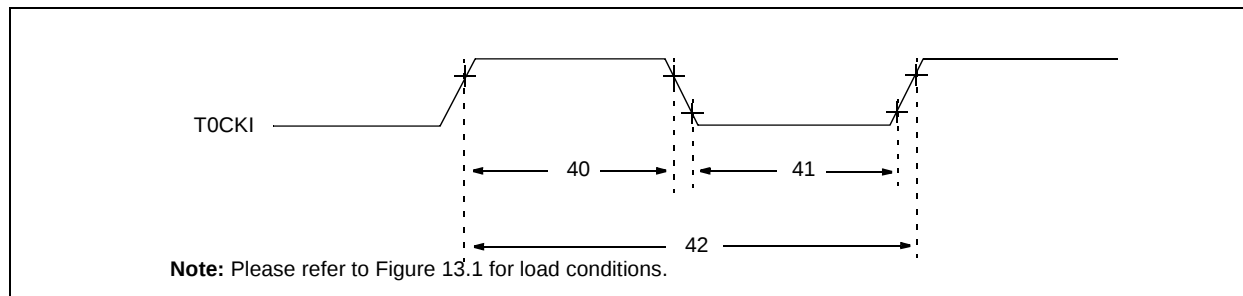


TABLE 13-4: TIMER0 CLOCK REQUIREMENTS - PIC16CR54A

AC Characteristics		Standard Operating Conditions (unless otherwise specified)					
		Operating Temperature					
		0°C ≤ TA ≤ +70°C for commercial					
		-40°C ≤ TA ≤ +85°C for industrial					
		-40°C ≤ TA ≤ +125°C for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width					
		- No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width					
		- No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period	20 or $\frac{TCY + 40^*}{N}$	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C5X

15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial) PIC16C54A-04I, 10I, 20I (Industrial) PIC16LC54A-04 (Commercial) PIC16LC54A-04I (Industrial)

PIC16LC54A-04 PIC16LC54A-04I (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial					
PIC16C54A-04, 10, 20 PIC16C54A-04I, 10I, 20I (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial					
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage					
		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.0 4.5	— —	6.25 5.5	V V	RC, XT and LP modes HS mode
D002	VDR	RAM Data Retention Voltage⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D005	IDD	Supply Current⁽²⁾					
		PIC16LC5X	—	0.5	2.5	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
			—	11	27	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial
D005A			—	11	35	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial
		PIC16C5X	—	1.8	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
			—	2.4	8.0	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	4.5	16	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	14	29	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Commercial
			—	17	37	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

PIC16C5X

15.3 DC Characteristics: PIC16LV54A-02 (Commercial) PIC16LV54A-02I (Industrial)

PIC16LV54A-02 PIC16LV54A-02I (Commercial, Industrial)			Standard Operating Conditions (unless otherwise specified)				
			Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-20^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D001	V _{DD}	Supply Voltage RC and XT modes	2.0	—	3.8	V	
D002	V _{DR}	RAM Data Retention Voltage⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	V _{POR}	V_{DD} Start Voltage to ensure Power-on Reset	—	V _{SS}	—	V	See Section 5.1 for details on Power-on Reset
D004	S _{VDD}	V_{DD} Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	I _{DD}	Supply Current⁽²⁾ RC ⁽³⁾ and XT modes LP mode, Commercial LP mode, Industrial	— — —	0.5 11 14	— 27 35	mA μA μA	F _{OSC} = 2.0 MHz, V _{DD} = 3.0V F _{OSC} = 32 kHz, V _{DD} = 2.5V WDT disabled F _{OSC} = 32 kHz, V _{DD} = 2.5V WDT disabled
D020	I _{PD}	Power-down Current^(2,4) Commercial Commercial Industrial Industrial	— — — —	2.5 0.25 3.5 0.3	12 4.0 14 5.0	μA μA μA μA	V _{DD} = 2.5V, WDT enabled V _{DD} = 2.5V, WDT disabled V _{DD} = 2.5V, WDT enabled V _{DD} = 2.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which V_{DD} can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all I_{DD} measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to V_{SS}, T_{0CKI} = V_{DD}, MCLR = V_{DD}; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through R_{EXT}. The current through the resistor can be estimated by the formula: I_R = V_{DD}/2R_{EXT} (mA) with R_{EXT} in kΩ.

4: The oscillator start-up time can be as much as 8 seconds for XT and LP oscillator selection on wake-up from SLEEP mode or during initial power-up.

15.4 DC Characteristics: PIC16C54A-04, 10, 20, PIC16LC54A-04, PIC16LV54A-02 (Commercial) PIC16C54A-04I, 10I, 20I, PIC16LC54A-04I, PIC16LV54A-02I (Industrial) PIC16C54A-04E, 10E, 20E, PIC16LC54A-04E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-20^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial-PIC16LV54A-02I $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	VSS VSS VSS VSS VSS	— — — — —	0.2 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.3 VDD	V V V V V	Pin at hi-impedance RC mode only ⁽³⁾ XT, HS and LP modes
D040	VIH	Input High Voltage I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	0.2 VDD + 1 2.0 0.85 VDD 0.85 VDD 0.85 VDD 0.7 VDD	— — — — — —	VDD VDD VDD VDD VDD VDD	V V V V V V	For all VDD ⁽⁴⁾ 4.0V < VDD ≤ 5.5V ⁽⁴⁾ RC mode only ⁽³⁾ XT, HS and LP modes
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	—	—	V	
D060	IIL	Input Leakage Current^(1,2) I/O ports MCLR MCLR T0CKI OSC1	-1.0 -5.0 — -3.0 -3.0	0.5 — 0.5 0.5 0.5	+1.0 +5.0 +3.0 +3.0 —	μA μA μA μA μA	For VDD ≤ 5.5V: VSS ≤ VPIN ≤ VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS ≤ VPIN ≤ VDD VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	Output Low Voltage I/O ports OSC2/CLKOUT	— —	— —	0.6 0.6	V V	IO _L = 8.7 mA, VDD = 4.5V IO _L = 1.6 mA, VDD = 4.5V, RC mode only
	VOH	Output High Voltage⁽²⁾ I/O ports OSC2/CLKOUT	VDD - 0.7 VDD - 0.7	— —	— —	V V	IO _H = -5.4 mA, VDD = 4.5V IO _H = -1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

FIGURE 15-3: CLKOUT AND I/O TIMING - PIC16C54A

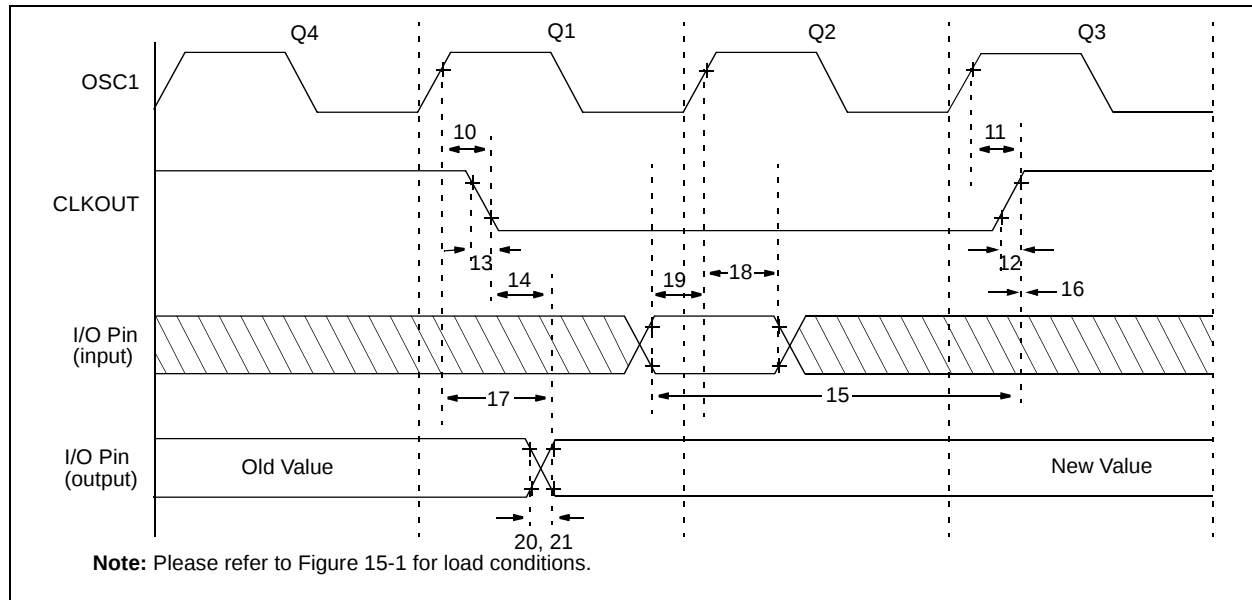


TABLE 15-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54A

Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-20^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial - PIC16LV54A-02I $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended						
AC Characteristics						
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	—	15	30**	ns
12	TckR	CLKOUT rise time ⁽¹⁾	—	5.0	15**	ns
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ ⁽¹⁾	$0.25 \text{ TCY} + 30^*$	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ ⁽¹⁾	0^*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is $4 \times T_{osc}$.

2: Please refer to Figure 15-1 for load conditions.

FIGURE 16-10: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)

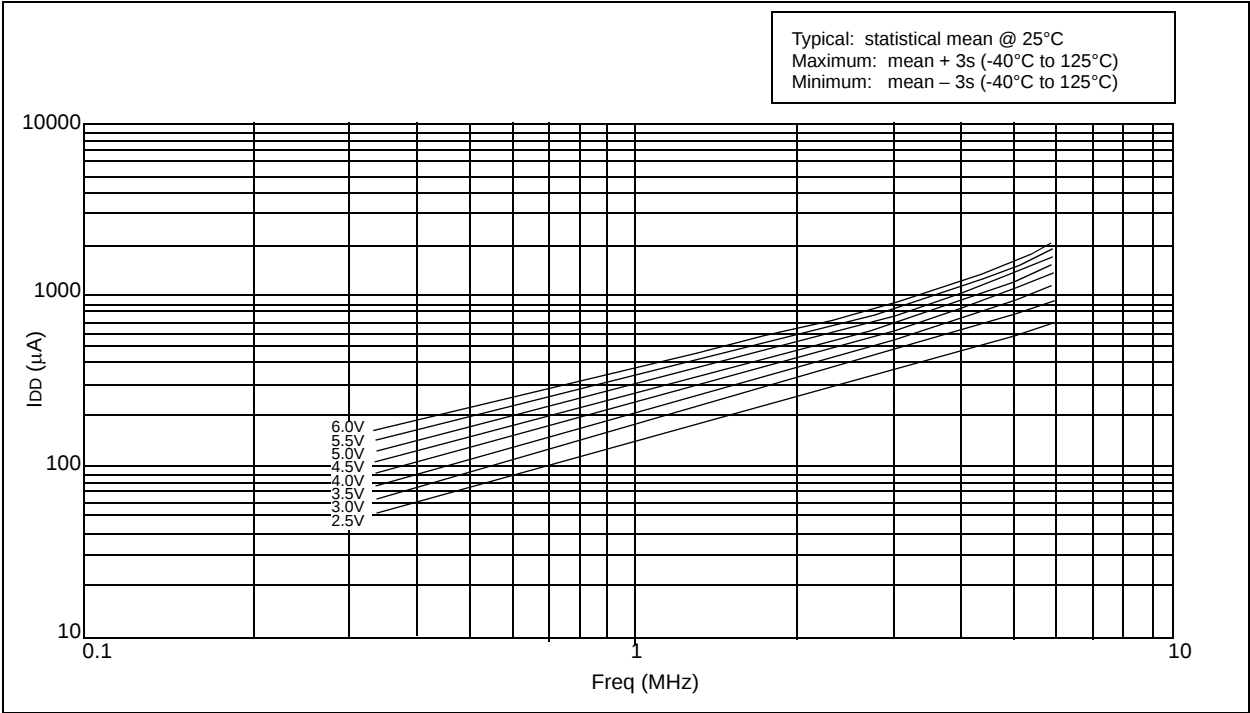


FIGURE 16-11: MAXIMUM I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, -40°C to +85°C)

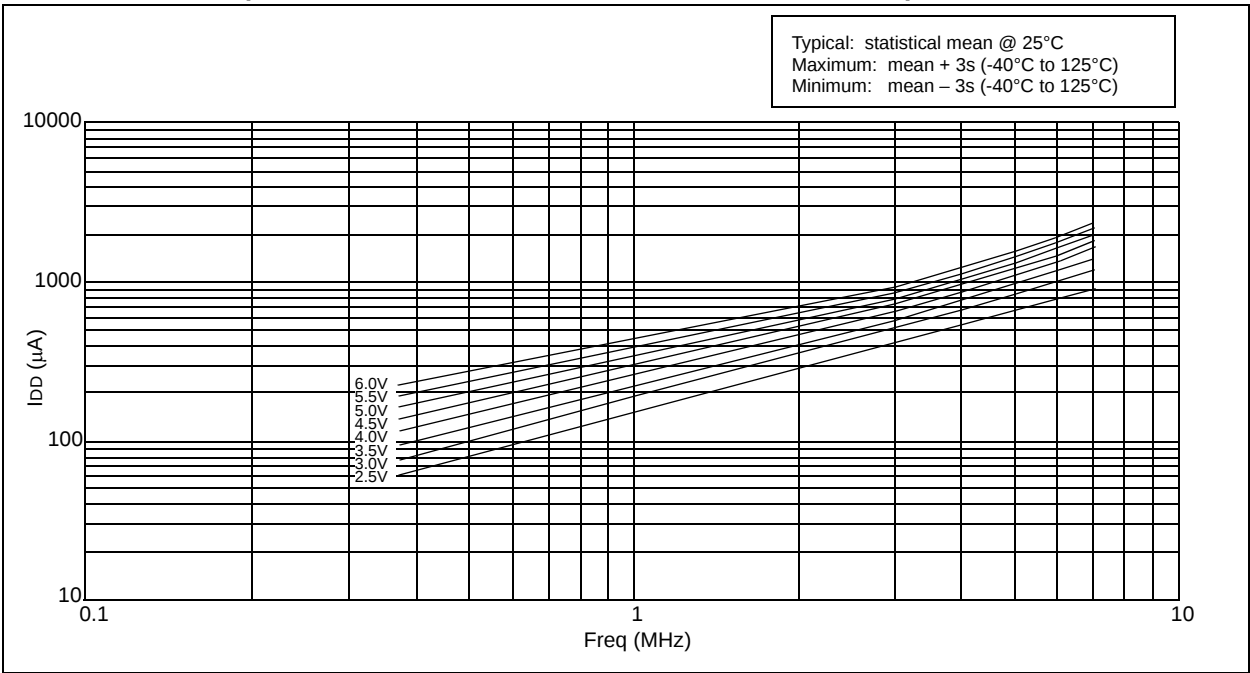


FIGURE 16-18: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

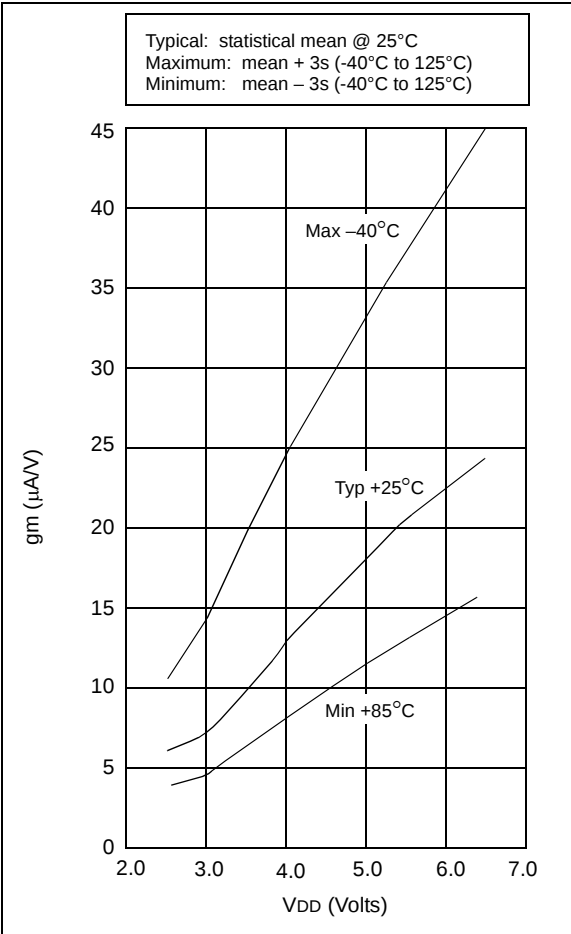
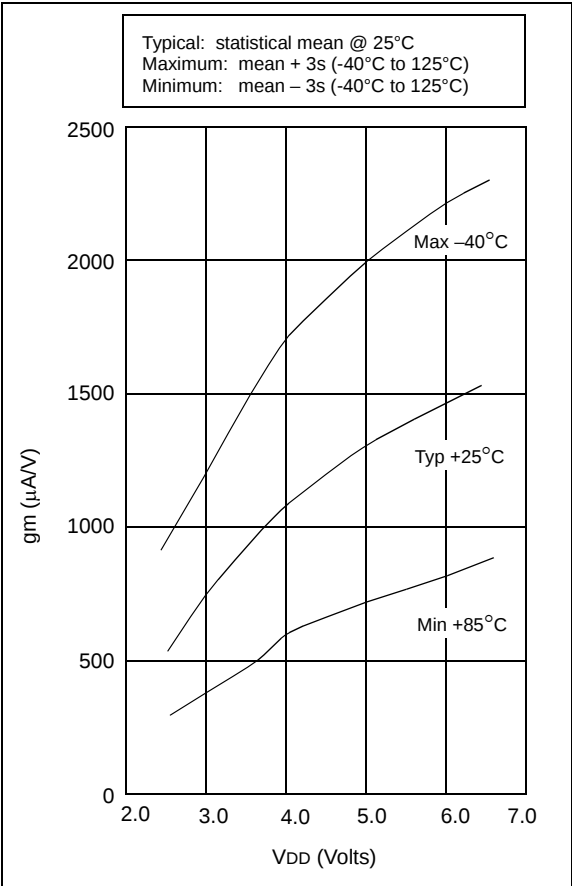


FIGURE 16-19: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



17.0 ELECTRICAL CHARACTERISTICS - PIC16LC54A

Absolute Maximum Ratings^(†)

Ambient temperature under bias	–55°C to +125°C
Storage temperature	–65°C to +150°C
Voltage on V _{DD} with respect to V _{SS}	0 to +7.5V
Voltage on MCLR with respect to V _{SS}	0 to +14V
Voltage on all other pins with respect to V _{SS}	–0.6V to (V _{DD} + 0.6V)
Total power dissipation ⁽¹⁾	800 mW
Max. current out of V _{SS} pin	150 mA
Max. current into V _{DD} pin	100 mA
Max. current into an input pin (T _{0CKI} only)	±500 µA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O (Port A, B or C)	50 mA
Max. output current sunk by a single I/O (Port A, B or C)	50 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIC16C5X

19.2 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-40 (Commercial)⁽¹⁾

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified)				
			Operating Temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	V _{IL}	Input Low Voltage I/O Ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1	V _{SS} V _{SS} V _{SS} V _{SS}	— — — —	0.8 0.15 V _{DD} 0.15 V _{DD} 0.2 V _{DD}	V V V V	4.5V < V _{DD} ≤ 5.5V HS, 20 MHz ≤ F _{OSC} ≤ 40 MHz
D040	V _{IH}	Input High Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1	2.0 0.85 V _{DD} 0.85 V _{DD} 0.8 V _{DD}	— — — —	V _{DD} V _{DD} V _{DD} V _{DD}	V V V V	4.5V < V _{DD} ≤ 5.5V HS, 20 MHz ≤ F _{OSC} ≤ 40 MHz
D050	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.15 V _{DD} *	—	—	V	
D060	I _{IL}	Input Leakage Current^(2,3) I/O ports MCLR MCLR T0CKI OSC1	-1.0 -5.0 — -3.0 -3.0	0.5 — 0.5 0.5 0.5	+1.0 +5.0 +3.0 +3.0 —	μA μA μA μA μA	For V_{DD} ≤ 5.5V: V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance V _{PIN} = V _{SS} + 0.25V V _{PIN} = V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} , HS
D080	V _{OL}	Output Low Voltage I/O ports	—	—	0.6	V	I _{OL} = 8.7 mA, V _{DD} = 4.5V
D090	V _{OH}	Output High Voltage⁽³⁾ I/O ports	V _{DD} - 0.7	—	—	V	I _{OH} = -5.4 mA, V _{DD} = 4.5V

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- Note 1:** Device operation between 20 MHz to 40 MHz requires the following: V_{DD} between 4.5V to 5.5V, OSC1 pin externally driven, OSC2 pin not connected and HS oscillator mode and commercial temperatures. For operation between DC and 20 MHz, See Section 17.3.
- 2:** The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.
- 3:** Negative current is defined as coming out of the pin.

FIGURE 19-4: CLKOUT AND I/O TIMING - PIC16C5X-40

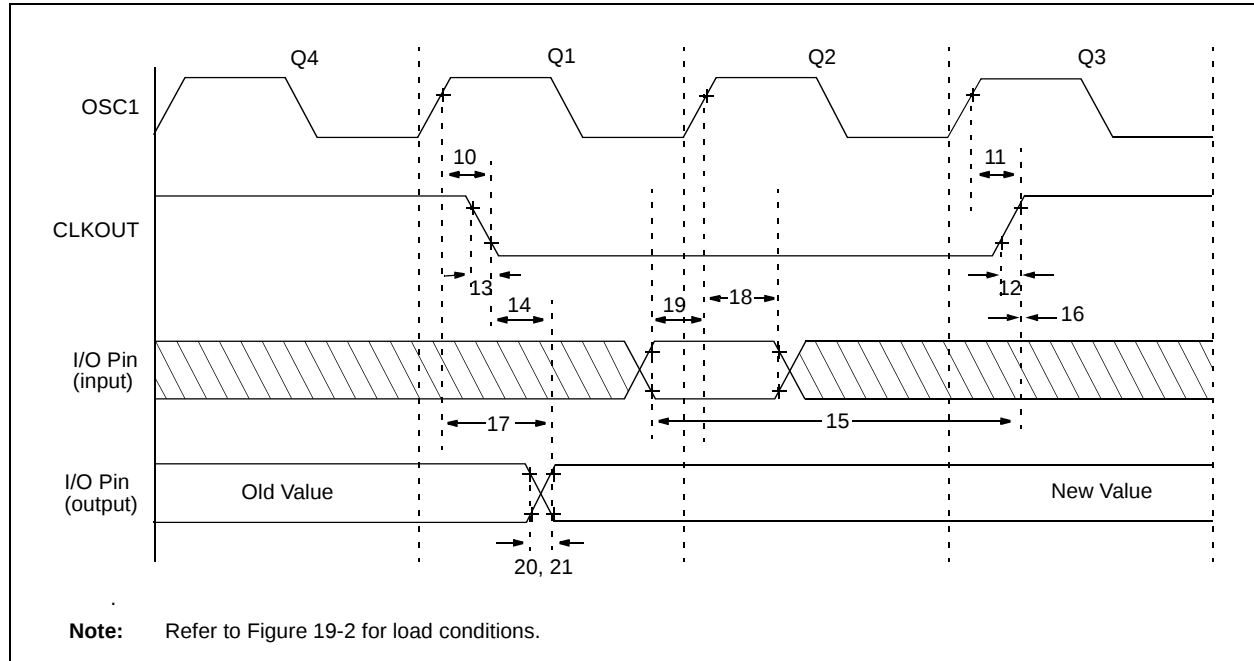


TABLE 19-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X-40

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ^(1,2)	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ^(1,2)	—	15	30**	ns
12	TckR	CLKOUT rise time ^(1,2)	—	5.0	15**	ns
13	TckF	CLKOUT fall time ^(1,2)	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ^(1,2)	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ ^(1,2)	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ ^(1,2)	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	—	—	100	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

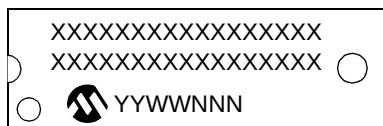
Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Refer to Figure 19-2 for load conditions.

21.0 PACKAGING INFORMATION

21.1 Package Marketing Information

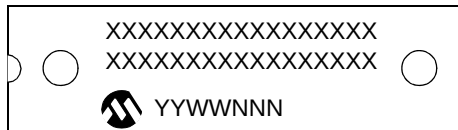
18-Lead PDIP



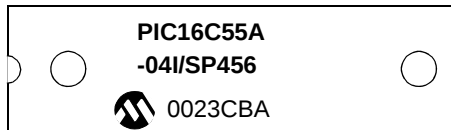
Example



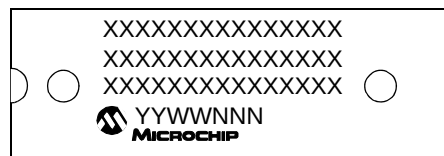
28-Lead Skinny PDIP (.300")



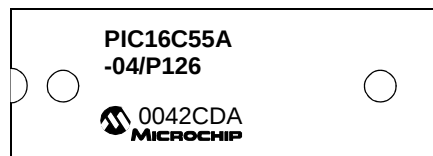
Example



28-Lead PDIP (.600")



Example



18-Lead SOIC



Example



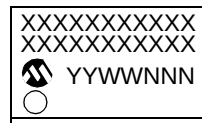
28-Lead SOIC



Example



20-Lead SSOP



Example



28-Lead SSOP

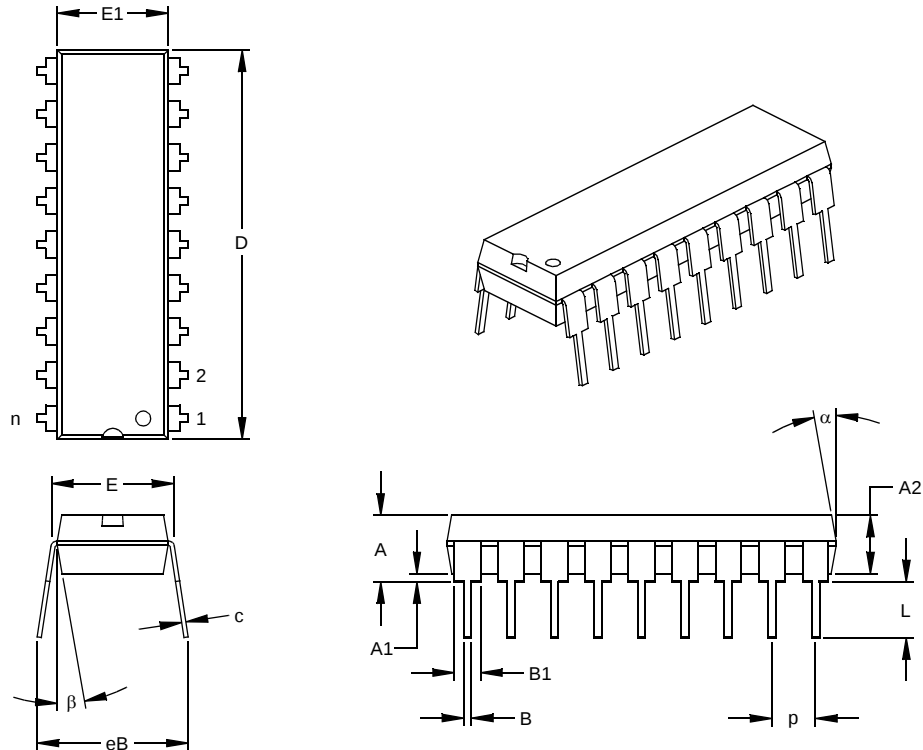


Example



18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

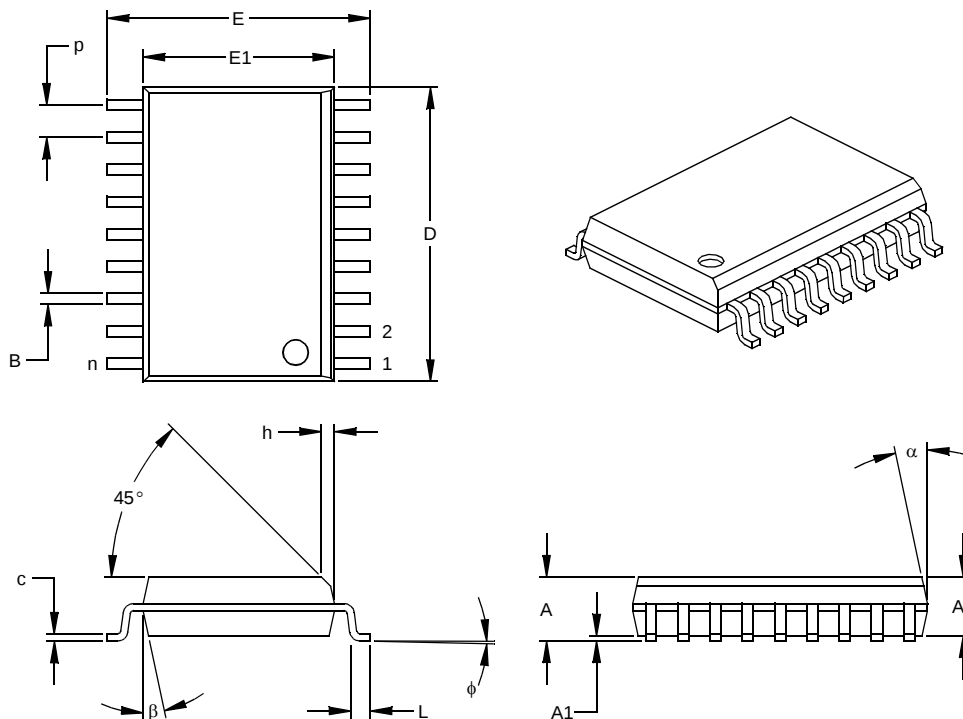
JEDEC Equivalent: MS-001

Drawing No. C04-007

PIC16C5X

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

INDEX

A

Absolute Maximum Ratings	
PIC16C54/55/56/57	67
PIC16C54A	103
PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/ C58B/CR58B	131
PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/ C58B/CR58B-40	155
PIC16CR54A	79
ADDWF	51
ALU	9
ANDLW	51
ANDWF	51
Applications	5
Architectural Overview	9
Assembler	
MPASM Assembler	61

B

Block Diagram	
On-Chip Reset Circuit	20
PIC16C5X Series	10
Timer0	37
TMR0/WDT Prescaler	41
Watchdog Timer	46
Brown-Out Protection Circuit	23
BSF	52
BTFSC	52
BTFSS	52

C

CALL	31, 53
Carry (C) bit	9, 29
Clocking Scheme	13
CLRF	53
CLRW	53
CLRWD	53
CMOS Technology	1
Code Protection	43, 47
COMF	54
Compatibility	182
Configuration Bits	44

D

Data Memory Organization	26
DC Characteristics	
PIC16C54/55/56/57	
Commercial	68, 71
Extended	70, 72
Industrial	69, 71
PIC16C54A	
Commercial	104, 109
Extended	106, 109
Industrial	104, 109
PIC16C54C/C55A/C56A/C57C/C58B-40	
Commercial	157, 158
PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/ C58B/CR58B	
Commercial	134, 138
Extended	137, 138
Industrial	134, 138
PIC16CR54A	
Commercial	80, 83

Extended	82, 84
Industrial	80, 83
PIC16LV54A	
Commercial	108, 109
Industrial	108, 109
DECF	54
DECFSZ	54
Development Support	61
Device Characterization	
PIC16C54/55/56/57/CR54A	91
PIC16C54A	117
PIC16C54C/C55A/C56A/C57C/C58B-40	165
Device Reset Timer (DRT)	23
Device Varieties	7
Digit Carry (DC) bit	9, 29
DRT	23

E

Electrical Specifications	
PIC16C54/55/56/57	67
PIC16C54A	103
PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/ C58B/CR58B	131
PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/ C58B/CR58B-40	155
PIC16CR54A	79
Errata	3
External Power-On Reset Circuit	21

F

Family of Devices	
PIC16C5X	6
FSR Register	33
Value on reset	20

G

General Purpose Registers	
Value on reset	20
GOTO	31, 55

H

High-Performance RISC CPU	1
---------------------------	---

I

I/O Interfacing	35
I/O Ports	35
I/O Programming Considerations	36
ICEPIC In-Circuit Emulator	62
ID Locations	43, 47
INCF	55
INCFSZ	55
INDF Register	33
Value on reset	20
Indirect Data Addressing	33
Instruction Cycle	13
Instruction Flow/Pipelining	13
Instruction Set Summary	49
IORLW	56
IORWF	56

K

KeeLoq Evaluation and Programming Tools	64
---	----

L

Loading of PC	31
---------------	----

Worldwide Sales and Service

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://www.microchip.com/support>
Web Address:
www.microchip.com

Atlanta

Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Boston

Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago

Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland

Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas

Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit

Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Indianapolis

Noblesville, IN
Tel: 317-773-8323
Fax: 317-773-5453

Los Angeles

Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

Santa Clara

Santa Clara, CA
Tel: 408-961-6444
Fax: 408-961-6445

Toronto

Mississauga, Ontario,
Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2401-1200
Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8569-7000
Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hangzhou

Tel: 86-571-2819-3187
Fax: 86-571-2819-3189

China - Hong Kong SAR

Tel: 852-2943-5100
Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8864-2200
Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Osaka

Tel: 81-6-6152-7160
Fax: 81-6-6152-9310

Japan - Tokyo

Tel: 81-3-6880-3770
Fax: 81-3-6880-3771

Korea - Daegu

Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-5778-366
Fax: 886-3-5770-955

Taiwan - Kaohsiung

Tel: 886-7-213-7828
Fax: 886-7-330-9305

Taiwan - Taipei

Tel: 886-2-2508-8600
Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

UK - Wokingham

Tel: 44-118-921-5869
Fax: 44-118-921-5820

11/29/12